

# UHMWPE POROUS MATERIAL SUNMAP LC-TW1

## **Features**

- As SUNMAP is a porous sintered material having an open-cell structure; it offers the excellent air and moisture permeability.
- As SUNMAP is made of porous UHMWPE having high wear resistance and low friction coefficient the slip properties of SUNMAP is enhanced.
- SUNMAP offers good chemical resistance against typical acids and alkalis.
- Antistatic

#### **Structure**



Fig. 1

Table 1. General Properties						
Item	Unit	Characteristic value			Test method	
Thickness	mm	0.2	0.3	0.5	_	
Air permeability	cm <sup>3</sup> /cm <sup>2</sup> /sec	8	7	1.4	JIS L1096	
Pore size	μm	17			—	
Porosity	%	30			—	
Tensile strength	MPa	12			JIS C2107	
Elongation	%	90			JIS C2107	
Hardness	Shore D	48			ASTM D2240	
Surface Roughness(Ra)	μm	2.0			JIS B 0601	
Coefficient of kinetic friction	_	0.1			JIS K7125	
Surface resistance	Ω/□	1×10 <sup>10</sup>			JIS K7194	

## **Properties**

1/2 LC-TW1\_03E 2017.12.4

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## Product size

	Table 2 Roll type		
Thickness(mm)	Width (mm)	Length (m)	
0.2			
0.3	600~1000	10	
0.5			

#### **Applications**

- In ceramic condenser manufacturing process, SUNMAP is used as "shock-absorber".
- In LCD manufacturing process, SUNMAP is used as "shock-absorber".

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